

## General Description

MY740P the silicon N-channel Enhanced VDMOSFETs, is obtained by the self-aligned planar Technology which reduce the conduction loss, improve switching performance and enhance the avalanche energy. The transistor can be used in various power switching circuit for system miniaturization and higher efficiency.

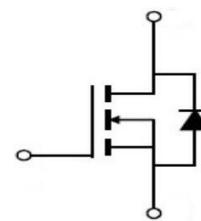
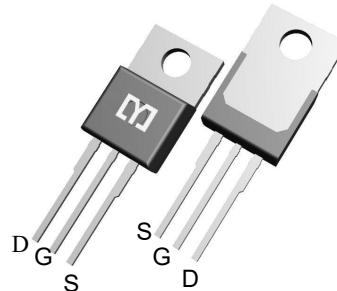


## Features

V <sub>DSS</sub>	450	V
I <sub>D</sub>	10	A
P <sub>D</sub> (T <sub>C</sub> =25°C)	135	W
R <sub>DS(ON)</sub> (at V <sub>GS</sub> =10V)	0.53	Ω

## Application

- Battery protection
- Load switch
- Uninterruptible power supply



## Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
MY740P	TO-220	MY740P	1000

## Absolute Maximum Ratings (T<sub>c</sub>=25°C unless otherwise noted)

Symbol	Parameters	Ratings	Unit
V <sub>DSS</sub>	Drain-Source Voltage	450	V
V <sub>GS</sub>	Gate-Source Voltage-Continuous	±30	V
I <sub>D</sub>	Drain Current-Continuous (Note 2)	10	A
I <sub>DM</sub>	Drain Current-Single Plused (Note 1)	40	A
P <sub>D</sub>	Power Dissipation (Note 2)	135	W
T <sub>j</sub>	Max.Operating junction temperature	150	°C

**Electrical Characteristics** at  $T_j=25\text{ }^\circ\text{C}$  unless otherwise specified

Symbol	Parameters	Min	Typ	Max	Units	Conditions
<b>Static Characteristics</b>						
$B_{VDSS}$	Drain-Source Breakdown VoltageCurrent (Note 1)	450	--	--	V	$I_D=250\mu\text{A}$ , $V_{GS}=0\text{V}$ , $T_j=25^\circ\text{C}$
$V_{GS(th)}$	Gate Threshold Voltage	2.0	--	4.0	V	$V_{DS}=V_{GS}$ , $I_D=250\mu\text{A}$
$R_{DS(on)}$	Drain-Source On-Resistance	--	0.48	0.53	$\Omega$	$V_{GS}=10\text{V}$ , $I_D=1\text{A}$
$I_{GSS}$	Gate-Body Leakage Current	--	--	$\pm 100$	nA	$V_{GS}=\pm 30\text{V}$ , $V_{DS}=0$
$I_{DSS}$	Zero Gate Voltage Drain Current	--	--	1	$\mu\text{A}$	$V_{DS}=400\text{V}$ , $V_{GS}=0$
$g_{fs}$	Forward Transconductance	5.8	--	--	S	$V_{DS}=15\text{V}$ , $I_D=5\text{A}$

### Switching Characteristics

T <sub>d(on)</sub>	Turn-On Delay Time	--	17	--	ns	V <sub>DS</sub> =250V, I <sub>D</sub> =10A, R <sub>G</sub> =25Ω (Note 2)
T <sub>r</sub>	Rise Time	--	10	--	ns	
T <sub>d(off)</sub>	Turn-Off Delay Time	--	10	--	ns	
T <sub>f</sub>	Fall Time	--	10	--	ns	
Q <sub>g</sub>	Total Gate Charge	--	35	50	nC	V <sub>DS</sub> =400V V <sub>GS</sub> =10V, I <sub>D</sub> =10A (Note 2)
Q <sub>gs</sub>	Gate-Source Charge	--	11	--	nC	
Q <sub>gd</sub>	Gate-Drain Charge	--	12	--	nC	

### Dynamic Characteristics

C <sub>iss</sub>	Input Capacitance	--	750	--	pF	V <sub>DS</sub> =25V, V <sub>GS</sub> =0, f=1MHz
C <sub>oss</sub>	Output Capacitance	--	220	--	pF	
C <sub>rss</sub>	Reverse Transfer Capacitance	--	27	--	pF	
I <sub>s</sub>	Continuous Drain-Source Diode Forward Current (Note 2)	--	--	10	A	
V <sub>SD</sub>	Diode Forward On-Voltage	--	--	1.4	V	I <sub>s</sub> =5A, V <sub>GS</sub> =0
R <sub>th(j-c)</sub>	Thermal Resistance, Junction to Case	--	--	0.93	°C/W	

Note 1: Repetitive Rating : Pulse width limited by maximum junction temperature

Note 2: Pulse test: PW <= 300us , duty cycle <= 2%.